Special issue on design, test, integration and packaging of MEMS/MOEMS: DTIP, Cannes, 2014

Souhil Megherbi¹ · Bernd Michel²

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The Symposium on Design, Test, Integration and Packaging of MEMS/MOEMS (DTIP) was held in Cannes, France, 1–4 April 2014, as a follow up to previous issues held in 1999 and 2000 in Paris, France, in 2001, 2002, 2003 in Mandelieu-La Napoule, France, in 2004 and 2005 in Montreux, Switzerland, and in 2006, 2007 in Stresa, Italy, in 2008 in Nice, France, in 2009 in Rome, Italy, in 2010 in Seville, Spain in 2011 in Aix-en-Provence, France, and in Barcelona, Spain in 2013. This series of Symposia is a forum for scientists and engineers from academia, research institutes and industry to present and discuss the latest results in manufacturing microstructures and design tools to facilitate the conception of these microstructures. The Symposium is traditionally composed of 2 conferences running in parallel: one on CAD, Design and Test, and another one on Microfabrication, Integration and Packaging. In addition, participants of both conferences can attend invited talks, special sessions, and poster presentations for innovative ideas, scientific and technological advancement, new developments and emerging technologies.

This special issue is collecting reviewed and unabridged versions of papers presented at the Symposium. The papers have been again refereed, along the usual refereeing process in force at Microsystem Technologies. For the participants, it is a special occasion to promote their research and professional work.

For this year, 22 papers have been selected. They cover a broad range of topics as: assembly and packaging, modeling and characterization, RF MEMS, MOEMS, sensors and actuators, in-vitro diagnostic device, MEMS accelerometers, reliability Mems/Nems design, manufacturing and test, and materials for manufacturing. We hope that you will enjoy those technological and scientific contributions.

Prof. Souhil Megherbi
University Paris-Sud, France
DTIP—MIP Chair and Guest Editor
Journal Microsystem Technologies

Prof. Bernd Michel
Editor-in-chief
Journal Microsystem Technologies
Micro Materials Center Berlin

✉ Souhil Megherbi
souhil.megherbi@u-psud.fr
<http://www.ief.u-psud.fr>

¹ Institut d'Electronique Fondamentale, Bât 220,
Université Paris-Sud, 91405 Orsay, France

² Micro Materials Center, Microsystem Technologies,
Berlin, Germany